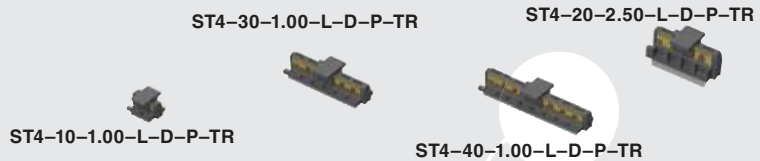




(0.40 mm) .0158"



ST4 SERIES

ULTRA FINE PITCH HEADER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ST4

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50μ" (1.27 μm) Ni

Operating Temp Range:

-55°C to +125°C

Current Rating:

1.6 A per pin

(1 pin powered per row)

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

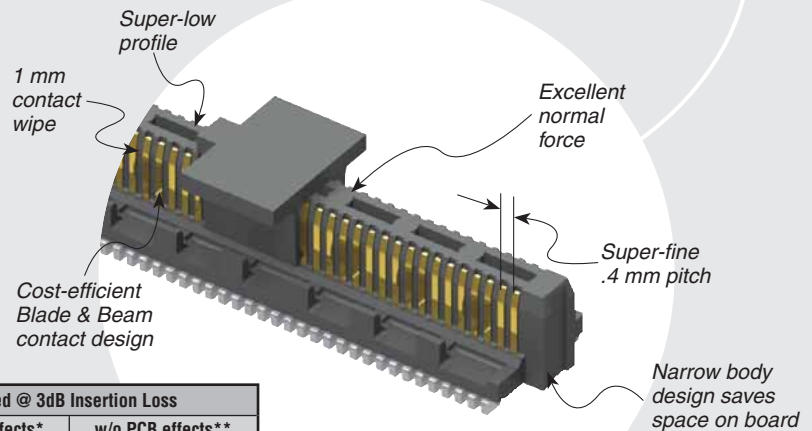
Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max

Mates with:

SS4



SS4/ST4 4 mm Stack Height	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
Single-Ended Signaling	7.0 GHz / 14 Gbps	13.5 GHz / 27 Gbps
Differential Pair Signaling	4.5 GHz / 9 Gbps	15.5 GHz / 31 Gbps

*Performance data includes effects of a non-optimized PCB.
 **Test board losses de-embedded from performance data.
 Performance data for other stack heights and complete test data available at www.samtec.com?ST4 or contact sig@samtec.com

FinalInch
CERTIFIED | 28+ Gbps

RECOGNITIONS

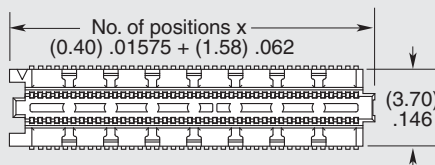
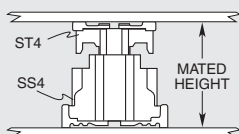
For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

ST4	POSITIONS PER ROW	LEAD STYLE	PLATING OPTION	D	P	TR
	-10, -20, -30, -40, -50	-1.00 = 1.00 mm -1.50 = 1.50 mm -2.50 = 2.50 mm	-L = 10μ" (0.25 μm) Gold on contact, Matte Tin on tail		(Required in callout) -P = Pick & Place Pad	(Required in callout) -TR = Tape & Reel

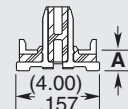
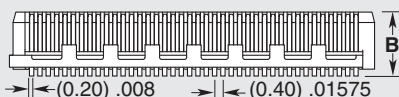
MATED HEIGHT



LEAD STYLE	A	B
-1.00	(1.00) .039	(3.08) .121
-1.50	(1.50) .059	(3.58) .141
-2.50	(2.50) .098	(4.58) .180

MATED HEIGHT*		
ST4 LEAD STYLE	SS4 LEAD STYLE	
	-3.00	-3.50
-1.00	(4.00) .157	(4.50) .177
-1.50	(4.50) .177	(5.00) .197
-2.50	(5.50) .217	(6.00) .236

*Processing conditions will affect mated height.



Note: Some lengths, styles and options are non-standard, non-returnable.